

- Functionally Equivalent to QS3245
- Standard '245-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Package Options Include Shrink Small-Outline (DB), Plastic Small-Outline (DW), and Thin Shrink Small-Outline (PW) Packages

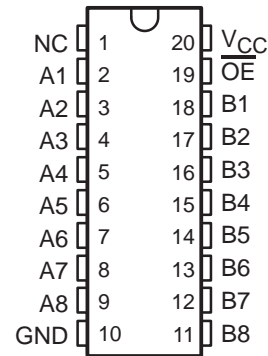
description

The SN74CBT3245 provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When output enable (\overline{OE}) is low, the switch is on and port A is connected to port B. When \overline{OE} is high, the switch is open and a high-impedance state exists between the two ports.

The SN74CBT3245 is characterized for operation from -40°C to 85°C .

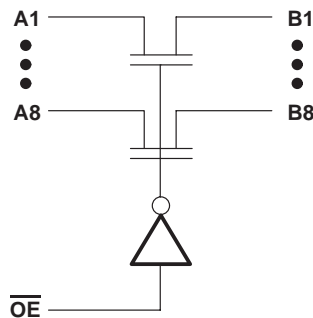
DB, DW, OR PW PACKAGE
(TOP VIEW)



FUNCTION TABLE

INPUT \overline{OE}	INPUTS/ OUTPUTS
	A, B
L	A = B
H	Z

logic diagram



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ADVANCE INFORMATION

SN74CBT3245

OCTAL BUS SWITCH

SCDS002C – NOVEMBER 1992 – REVISED MAY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2):	
DB package	0.6 W
DW package	1.6 W
PW package	0.7 W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2		V
V_{IL} Low-level control input voltage		0.8	V
T_A Operating free-air temperature	–40	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			–1.2	V
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 5.5\text{ V}$ or GND			±5	μA
I_{CC}	$V_{CC} = 5.5\text{ V}$, $I_O = 0$, $V_I = V_{CC}$ or GND			50	μA
ΔI_{CC}^{\S} Control pins	$V_{CC} = 5.5\text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND			3.5	mA
C_i Control pins	$V_I = 3\text{ V}$ or 0		3		pF
$C_{io}(\text{OFF})$	$V_O = 3\text{ V}$ or 0, $\overline{OE} = V_{CC}$		6		pF
r_{on}^{\parallel}	$V_{CC} = 4\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$				Ω
	$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 64\text{ mA}$		5	7	
	$V_{CC} = 4.5\text{ V}$, $V_I = 0$, $I_I = 30\text{ mA}$		5	7	
	$V_{CC} = 4.5\text{ V}$, $V_I = 2.4\text{ V}$, $I_I = 15\text{ mA}$		10	15	

[‡] All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

^{\S} This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

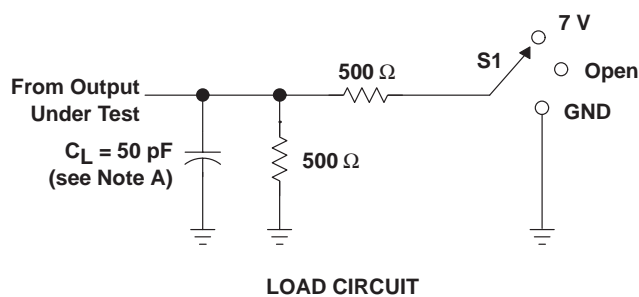
^{\parallel} Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

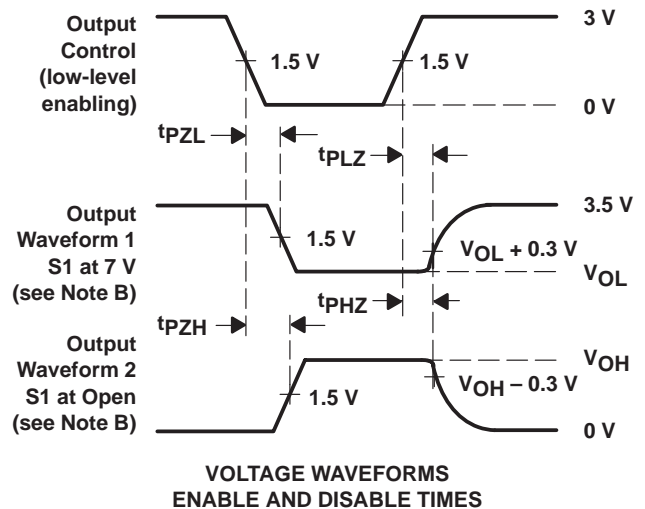
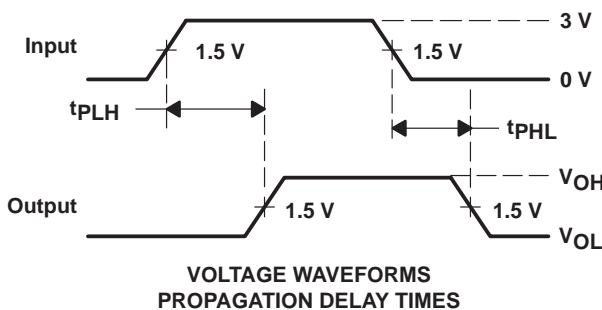
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{pd}^\dagger	A or B	B or A	0.25		ns
t_{en}	\overline{OE}	A or B			ns
t_{dis}	\overline{OE}	A or B			ns

[†] This parameter is characterized but not tested. This propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF.

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

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